Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-60	V
Collector-Emitter Voltage	V_{CEO}	-60	V
Emitter-Base Voltage	V_{EBO}	-5	V
Collector Current	I_C	-600	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P_D	200	mW
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	625	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Notes: 6. For a device mounted with the collector lead on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

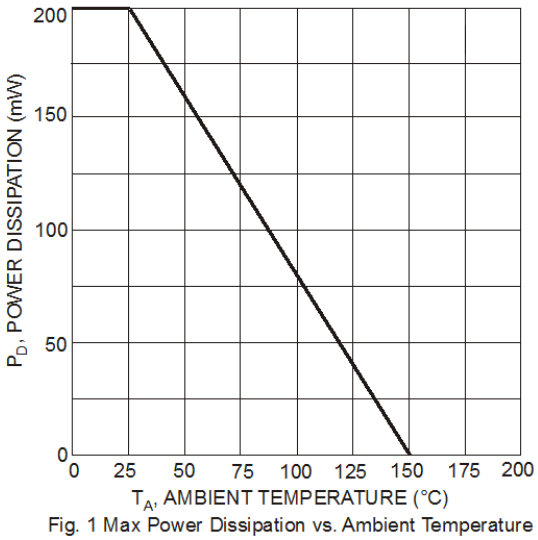


Fig. 1 Max Power Dissipation vs. Ambient Temperature

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)					
Collector-Base Breakdown Voltage	BV_{CBO}	-60	—	V	I_C = -10µA, I_E = 0
Collector-Emitter Breakdown Voltage	BV_{CEO}	-60	—	V	I_C = -10mA, I_B = 0
Emitter-Base Breakdown Voltage	BV_{EBO}	-5	—	V	I_E = -10µA, I_C = 0
Collector Base Cutoff Current	I_{CBO}	—	-10	nA µA	V_{CB} = -50V, I_E = 0 V_{CB} = -50V, I_E = 0, T_A = +125°C
Collector Cutoff Current	I_{CEX}	—	-50	nA	V_{CE} = -30V, $V_{EB(OF F)}$ = -0.5V
Base Cutoff Current	I_{BL}	—	-50	nA	V_{CE} = -30V, $V_{EB(OFF)}$ = -0.5V
ON CHARACTERISTICS (Note 8)					
DC Current Gain	h_{FE}	75 100 100 100 50	— — — 300 —	—	I_C = -100µA, V_{CE} = -10V I_C = -1mA, V_{CE} = -10V I_C = -10mA, V_{CE} = -10V I_C = -150mA, V_{CE} = -10V I_C = -500mA, V_{CE} = -10V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	—	-0.4 -1.6	V	I_C = -150mA, I_B = -15mA I_C = -500mA, I_B = -50mA
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	—	1.3 2.6	V	I_C = -150mA, I_B = -15mA I_C = -500mA, I_B = -50mA
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C_{obo}	—	8	pF	V_{CB} = -10V, f = 1.0MHz, I_E = 0
Input Capacitance	C_{ibo}	—	30	pF	V_{EB} = -2V, f = 1.0MHz, I_C = 0
Current Gain-Bandwidth Product	f_T	200	—	MHz	V_{CE} = -20V, I_C = -50mA, f = 100MHz
SWITCHING CHARACTERISTICS					
Turn-On Time	t_{on}	—	45	ns	V_{CC} = -30V, I_C = -150mA, I_{B1} = -15mA
Delay Time	t_d	—	10	ns	
Rise Time	t_r	—	40	ns	
Turn-Off Time	t_{off}	—	100	ns	V_{CC} = -6V, I_C = -150mA, I_{B1} = I_{B2} = -15mA
Storage Time	t_s	—	80	ns	
Fall Time	t_f	—	30	ns	

Note: 8. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

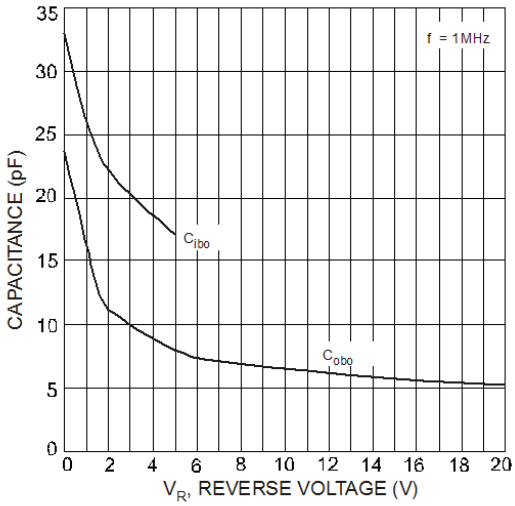


Fig. 2 Typical Capacitance Characteristics

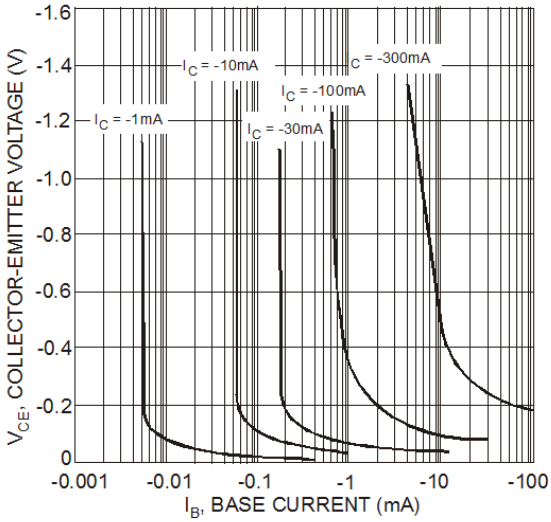


Fig. 3 Typical Collector Saturation Region

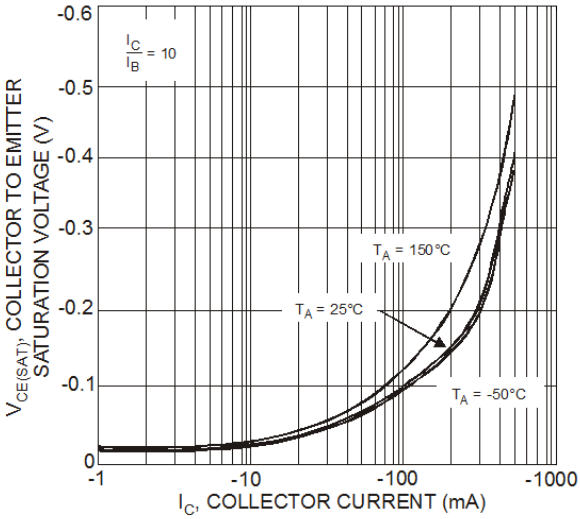


Fig. 4 Collector-Emitter Saturation Voltage vs. Collector Current

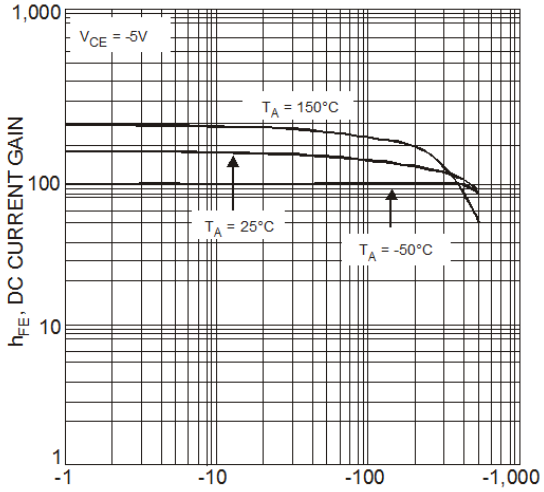


Fig. 5 DC Current Gain vs. Collector Current

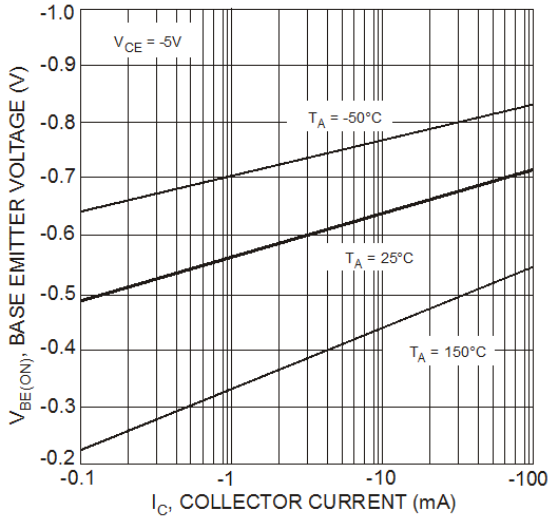


Fig. 6 Base-Emitter Voltage vs. Collector Current

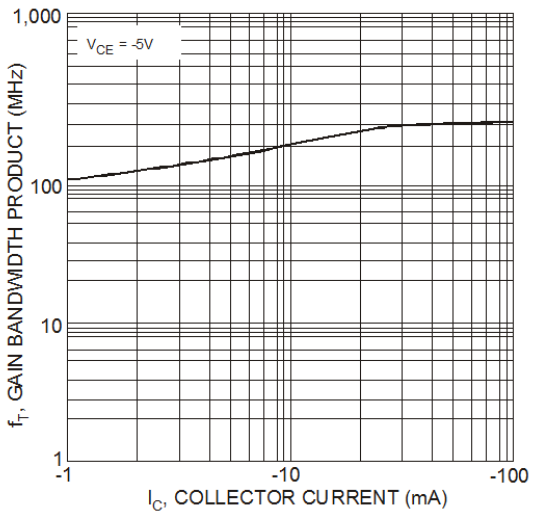
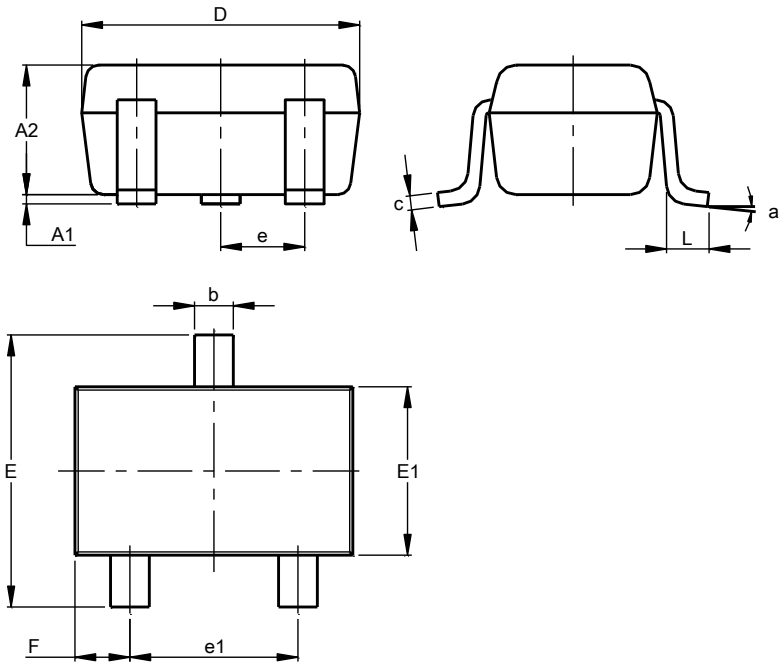


Fig. 7 Gain Bandwidth Product vs. Collector Current

Package Outline Dimensions

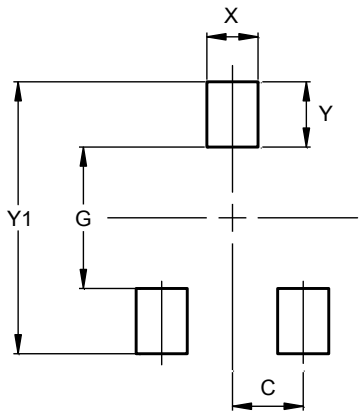
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT323			
Dim	**Min**	**Max**	**Typ**
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.25	0.40	0.30
c	0.10	0.18	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
e1	1.20	1.40	1.30
F	0.375	0.475	0.425
L	0.25	0.40	0.30
a	8°		
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.470
Y	0.600
Y1	2.500

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